503666714 01/27/2016

PATENT ASSIGNMENT COVER SHEET

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 SUBMISSION TYPE:
 NEW ASSIGNMENT

 NATURE OF CONVEYANCE:
 ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
MICHEL KOOPMANS	03/26/2014
SHIJIAN LUO	03/21/2014
DAVID R. HEMBREE	03/20/2014

RECEIVING PARTY DATA

Name:	MICRON TECHNOLOGY, INC.
Street Address:	8000 S. FEDERAL WAY
Internal Address:	P.O. BOX 6
City:	BOISE
State/Country:	IDAHO
Postal Code:	83707-0006

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	15007615

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ATTORNEY DOCKET NUMBER: 10829-9112.US01

NAME OF SUBMITTER: JANA BRATTON

SIGNATURE: /Jana Bratton/

DATE SIGNED: 01/27/2016

Total Attachments: 5

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PATENT 503666714 REEL: 037597 FRAME: 0373

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PATENT REEL: 037597 FRAME: 0374

ASSIGNMENT BY INVENTORS

This Assignment is by the following individuals (the "Assignors"):

- Michel Koopmans, having a mailing address of 2571 S. Waterbury Lane,
 Boise Idaho 83706;
- Shijian Luo, having a mailing address of 13358 W Tapatio Drive, Boise, Idaho 83713; and
- David R. Hembree, having a mailing address of 11074 W. Edgehill Drive,
 Boise, Idaho 83709.

The Assignors invented one or more certain inventions (the "Invention(s)") described in an application for Letters Patent of the United States titled STACKED SEMICONDUCTOR DIE ASSEMBLIES WITH IMPROVED THERMAL PERFORMANCE AND ASSOCIATED SYSTEMS AND METHODS, naming the Assignors as inventors, and filed on ______ as U.S. Application No. _____ (the "Application"). The Assignors authorize the Assignee, identified below, or its representatives to insert the application number and filing date of the Application when known.

Micron Technology, Inc., a corporation of Delaware having its principal place of business at 8000 S. Federal Way, P.O. Box 6, Boise, Idaho 83707-0006 (the "Assignee"), desires to acquire the entire right, title and interest in and to the Invention(s) and the Application, and in and to any patents (collectively, "Patents") that may be granted for the Invention(s) in the United States or in any foreign countries.

For valuable consideration, the receipt and sufficiency of which Assignors acknowledge, Assignors hereby sell, assign, and transfer to Assignee, its successors, legal representatives and assigns, the entire right, title and interest in and to: the Invention(s), the Application, and any Patents; any divisions, continuations, and continuations-in-part of the Application and any other application claiming priority rights from the Application; any reissues, reexaminations, or extensions of any and all

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Attorney Docket No. 10829-9112.US00 Micron Docket No. 2013-0497.00/US

Patents; the right to file foreign applications directly in the name of Assignee; and the right to claim priority rights deriving from the Application (collectively, the "Rights"). Assignors warrant that Assignors own the Rights, and that the Rights are unencumbered. Assignors also agree to not sign any writing or do any act conflicting with this assignment, and, without further compensation, sign all documents and do such additional acts as Assignee deem necessary or desirable to: perfect Assignee's enjoyment of the Rights; conduct proceedings regarding the Rights, including any litigation or interference proceedings; or perfect or defend title to the Rights. Assignors request the Commissioner of Patents to issue any Patent of the United States that may be issued on the Invention(s) to Assignee. This Assignment may be executed in counterparts.

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Date: 3/20/2014 Signature
Mtchel Koopmans
United States of America State of
Notary Public Notary Public Notary Public

Date: <u>03/2//wik</u> Signate	
,	Shijian Luo ∜
United States of America) State of	
On this 21st day of marc	h, <u>2014</u> before me
personally came Shijian Luo	, to me known to be the individual
described in and who executed the foregoi	ng instrument, and acknowledged execution
of the same.	
Drane V. Rangel	minimum management
Notary Public	
	S CUBLIC SO

Date: 3/20/14 Signature / auf /	N. Mahr
Óávid R. Hemb	pree
United States of America)	
State of) ss.	
County of <u>QQQ</u>)	
On this day of march personally came day of, to me ki	, <u>2014</u> before me
personally came <u>David R. Hembree</u> , to me ki	nown to be the individual
described in and who executed the foregoing instrument, and	l acknowledged execution
of the same.	
Diane Y. Rangel	The state of the s
Notary Public	SE MAN
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	B. A. S.
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RECORDED: 01/27/2016